

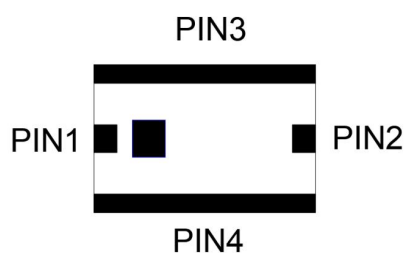
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

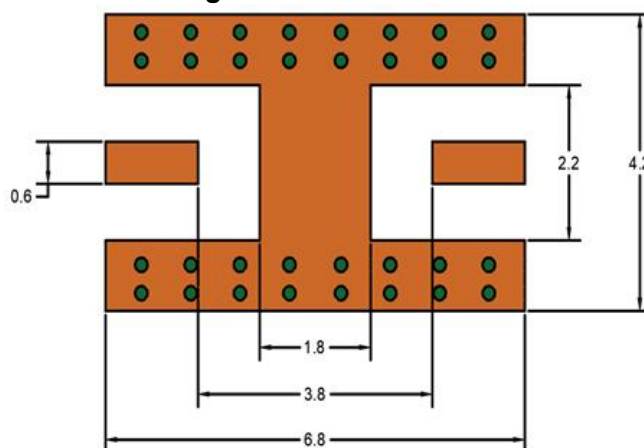
NO.	Parameter	Frequency (MHz)	SPEC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	1300~2300			3.0
2	-1.2 dB Bw (MHz)		1000		
3	VSWR				2.0
4	Attenuation (dB)	1100	25		
		2500	25		
5	In/Output Impedance (Ω)		50		
Operating & Storage Condition (Component)					
Operation Temperature Range: -40℃ ~ +85℃					
Storage Temperature Range: -40℃~ +85℃					
Storage Condition before Soldering (Included packaging material)					
Storage Temperature Range: +5 ~ +40 ℃					
Humidity: 30 to 70% relative humidity					

Construction



PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

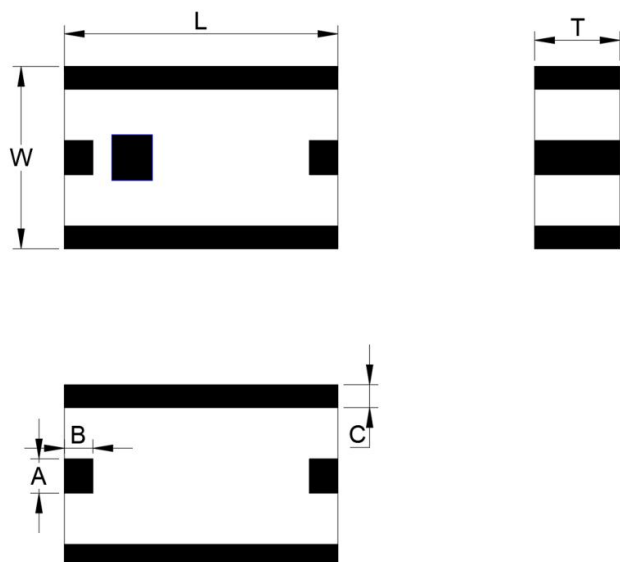
Mounting Considerations



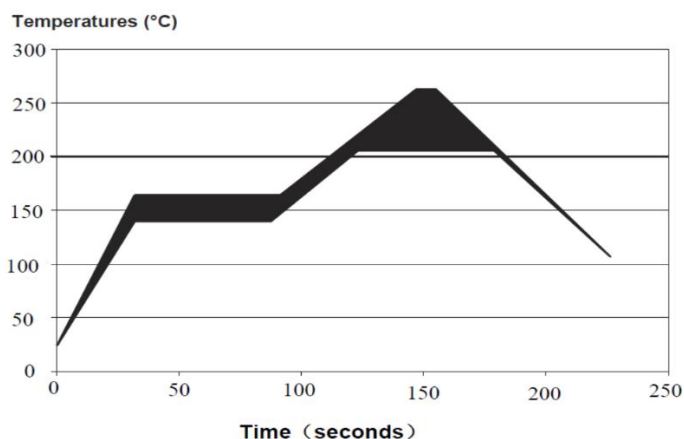
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	4.80±0.20
	W	3.20±0.20
	T	1.20±0.20
	A	0.60±0.10
	B	0.40±0.10
	C	0.4±0.10

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.